



Application

Heatpipe Towers are designed for cooling power electronics devices like IGBTs, power diodes, and power resistors. The high heat flux generated by these components is absorbed by the base plate and Heatpipes, which then transmit the heat isothermally to the fins.

This high-efficiency cooling solution is used in high-power applications across industrial, mobility, and renewable market segments. It is also ideal for retrofit applications where refurbished or redesigned systems need enhanced cooling performance for power electronics.

Advantages

- Increased Thermal Performance: Cooling high-power components is possible due to significantly better thermal performance compared to standard heatsinks.
- Optimal for Retrofit Applications: Ideal for increasing power rates in retrofit applications, requiring equal or less product space.
- Heatpipe Technology: The production process ensures maximum reliability, durability, and service life with no maintenance costs for the Heatpipes.

Design Properties

- Wide range of product dimension possible
- Various materials and coatings available
- Machined contact surface for optimized cooling
- CFD simulation for optimal thermal design

Manufacturing Process

Soldering process for maximum reliability, durability, and service life.

Fully soldered version for high performance demands

- low overall thermal resistance reduces the device's working temperature
- higher mechanical stability of the cooler

Stacked version for standard demands:

- reduced production costs
- good thermal contact of fin package to the Heatpipes

Thermal data

Applied module size:	62 × 122 mm
Numbers of modules:	6
Power per module:	600 W
Total power losses:	3600 W

